

DESCRIPTION:

The JOC302XD5 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic DIP5 package with different lead forming options. With the robust coplanar double mold structure, JOC302XD5 series provide the most stable isolation feature. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors up to 120 V_{AC} peripherals.

MAIN FEATURES

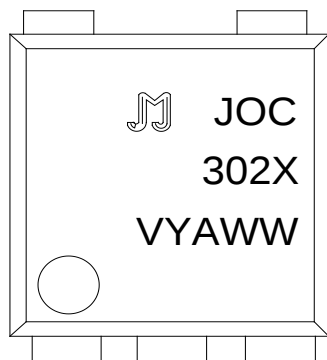
High isolation

	Junction Temperature	T _j	125	
	Output Power Dissipation	P _O	250	mW
	Power Dissipation Derating (T _a 125)	•P _D /	-3.33	mW/

/3.

ORDERING AND MARKING INFORMATION

MARKING INFORMATION



Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

FIG.2: On-state Terminal Current vs. Ambient Temperature I_F

FIG.7: Normalized On-state Terminal Voltage vs.
Ambient Temperature

FIG.8: On-state Terminal Voltage vs. On-

TEST CIRCUITS

FIG.12: Test Circuits of Turn On Time

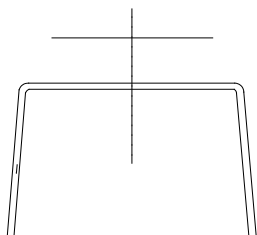
FIG.13: Waveforms of Turn On Time

Fig.14: Test Circuits of dV/dt

Fig.15: Waveforms of dV/dt

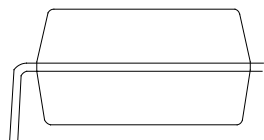
Package Dimension (Unit: mm)

Standard DIP Type:

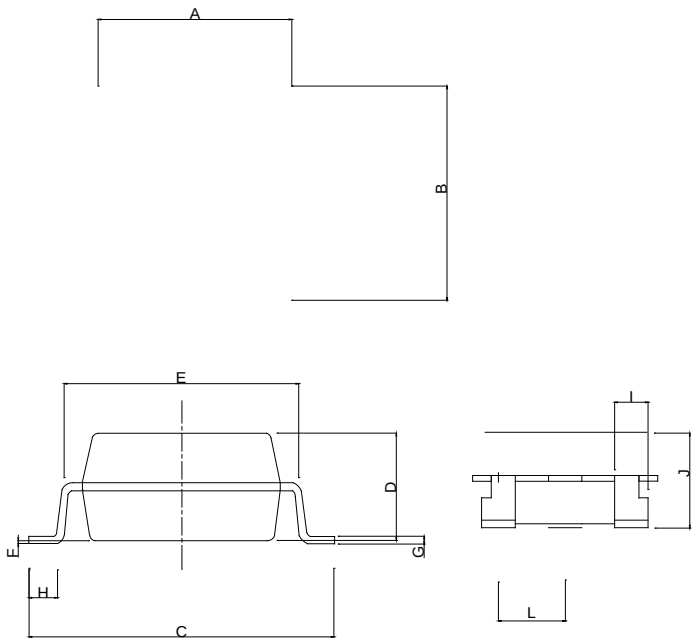


Option S Type:

:91 93.5417699 609.0826605 cm /CS0 CS731.724224S0 CS 35841m -185 809 I S Q q 0.0227635 0 0 -027491 172

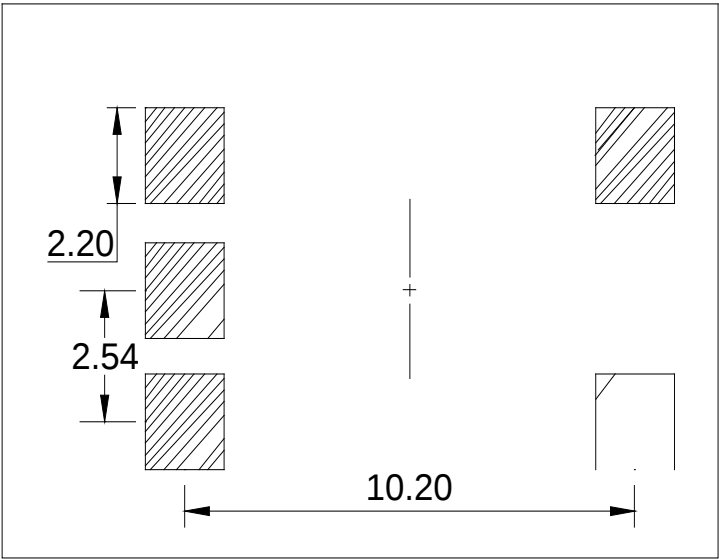


Option SLM Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.248		0.264
B	6.92		7.32	0.272		0.288
C	11.60		12.10	0.457		0.476
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.288		0.312
F			0.30			0.012
G						
H	0.50			0.020		
I	1.10		1.30	0.043		0.051
J	3.45		3.85	0.136		0.152
K						

Option SL



//

/

REFLOW INFORMATION



This image shows a completely blank white rectangular area enclosed within a thin black border. There are no markings, text, or illustrations present on the page.

HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360 ± 5
Soldering Time	3s max.

Document Revision History

Date	Revision	Changes
Apr.2, 2025	A.1.0	Last update
Nov.5, 2025	A.1.1	Add S&SLM package

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co., Ltd. assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document supersedes and replaces all information previously supplied.

is a registered trademark of Jiangsu JieJie Microelectronics Co., Ltd.

Copyright © 2025 Jiangsu JieJie Microelectronics Co., Ltd. All rights reserved.